



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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GC HEAT SINK COMPOUNDS

Chem

Meets Your Great Demands

The technology of today's electronic devices has increased current handling capacity. The additional heat buildup places great demands on heat sink materials. GC offers a complete line of heat sink compounds to meet these demands. The HTC product offers over twice the thermal conductivity of conventional products and is available in silicone and non-silicone versions. The water-soluble heat sink grease offers excellent thermal conductivity and easy cleanup. The standard silicone and non-silicone products continue to meet most requirements. See chart for typical properties.



Silicone (Z9)

Industry standard zinc oxide filled silicone heat sink grease for most applications. Will not soften at elevated temperatures or dry out or harden. Meets MIL-DTL-47113 Type 2

Part No. 10-8109	1 fl. oz. Tube
Part No. 10-8108	6.5 gms. Tube
Part No. 10-8106	1 lb. Jar plastic



HTC (High Thermal Conductivity)

Higher thermal conductivity formula has all the same benefits of conventional heat sink greases, plus is exceptionally stable in high humidity applications.

Part No. 10-8135	Silicone Based, 1 oz. Syringe
Part No. 10-8135-0001	Silicone Based, 1lb. Jar



Type 44 Non-Silicone

Compounded with 100% synthetic base stocks. Features excellent heat transfer efficiency, thermal stability, high flow rate, no separation, bleed or migration typical of silicone based greases.

MIL-DTL-47113 Type 2

Part No. 10-8118	1/2 fl. oz. Jar
Part No. 10-8120	1 fl. oz. Tube
Part No. 10-8126	1 lb. Jar

Heat Sink Properties (Typical)

Tests	Test Methods	10-8106 10-8108 10-8109 Standard Silicone	10-8118 10-8120 10-8126 Standard Non-Silicone	10-8135 H.T.C. Silicone
Appearance	Visual	White Paste	White Paste	Off-White Paste
Consistency Penetration 60 Strokes @ 77°F	ASTM D-217	340	260	250-350
Specific Gravity	ASTM D-70	2.2	2.5	2.7
Bleed, 24 Hrs. %Wt. 150°C 200°C	FTM-321 PTM-791.321	0.50	<0.5	0.3
Evaporation, 24 Hr. %Wt. 150°C 200°C	FTM-321 PTM-791.321-3M	0.50	0.1	0.3
Thermal Conductivity CAL/SEC/cm °C	Modified DSC	1.8 x 10 ⁻³	1.8 x 10 ⁻³	
	Hot Wire Method			4.35 x 10 ⁻³
Dielectric Strength 0.050" gap volts/mil.	ASTM D-149	400	420	343
Dielectric Constant 1000 Hz	ASTM D-150	4.9	4.5	5.14
Dissipation Factor 50 Hz, Ohm-cm 1,000 Hz, Ohm-cm	ASTM D-150	0.005 0.001	0.0029 0.0029	0.0031
Volume Resistivity Ohm-cm	ASTM D-257	1.96 x 10 ¹⁵	2 x 10 ¹⁵	1 x 10 ¹⁵
Operating Range		-67°F to 400°F	-22°F to 390°F	-55°C to 205°C
Arc Resistance, RT Unit: SEC	ASTM D-495	77	130	250
Shelf Life Months		60	60	60